

# MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RRM}$ $V_{RWM}$ $V_R$	40	V
Average Rectified Forward Current (At Rated $V_R$ , $T_C = 110^\circ\text{C}$ )	$I_O$	1.0	A
Peak Repetitive Forward Current (At Rated $V_R$ , Square Wave, 100 kHz, $T_C = 110^\circ\text{C}$ )	$I_{FRM}$	2.0	A
Non-Repetitive Peak Surge Current (Non-Repetitive peak surge current, halfwave, single phase, 60 Hz)	$I_{FSM}$	50	A
Storage Temperature	$T_{stg}$	-55 to 150	$^\circ\text{C}$
Operating Junction Temperature	$T_J$	-55 to 125	$^\circ\text{C}$
Voltage Rate of Change (Rated $V_R$ , $T_J = 25^\circ\text{C}$ )	$dv/dt$	10,000	$\text{V}/\mu\text{s}$

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

# THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal Resistance, Junction-to-Lead (Anode) (Note 1)	$R_{tjl}$	35	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Tab (Cathode) (Note 1)	$R_{tjtab}$	23	
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{tja}$	277	

1. Mounted with minimum recommended pad size, PC Board FR4, See Figures 9 & 10

# ELECTRICAL CHARACTERISTICS

Rating	Symbol	Value		Unit
Maximum Instantaneous Forward Voltage (Note 2), See Figure 2 ( $I_F = 0.1\text{ A}$ ) ( $I_F = 1.0\text{ A}$ ) ( $I_F = 3.0\text{ A}$ )	$V_F$	$T_J = 25^\circ\text{C}$	$T_J = 85^\circ\text{C}$	V
		0.36	0.30	
		0.55	0.515	
		0.85	0.88	
Maximum Instantaneous Reverse Current (Note 2), See Figure 4 ( $V_R = 40\text{ V}$ ) ( $V_R = 20\text{ V}$ )	$I_R$	$T_J = 25^\circ\text{C}$	$T_J = 85^\circ\text{C}$	mA
		0.5	25	
		0.15	18	

2. Pulse Test: Pulse Width  $\leq 250\text{ }\mu\text{s}$ , Duty Cycle  $\leq 2\%$

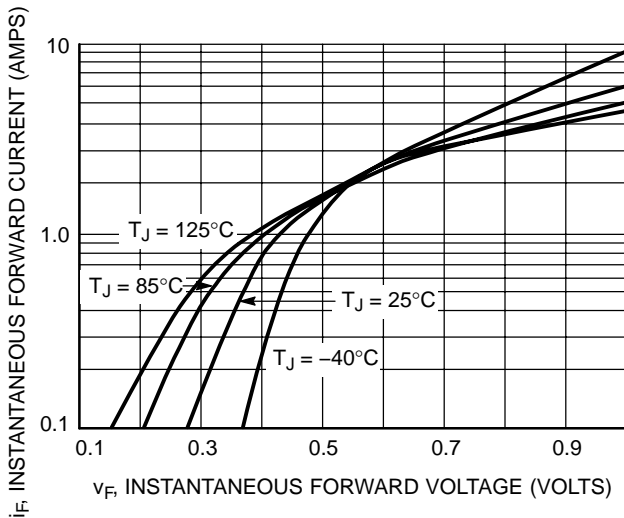


Figure 1. Typical Forward Voltage

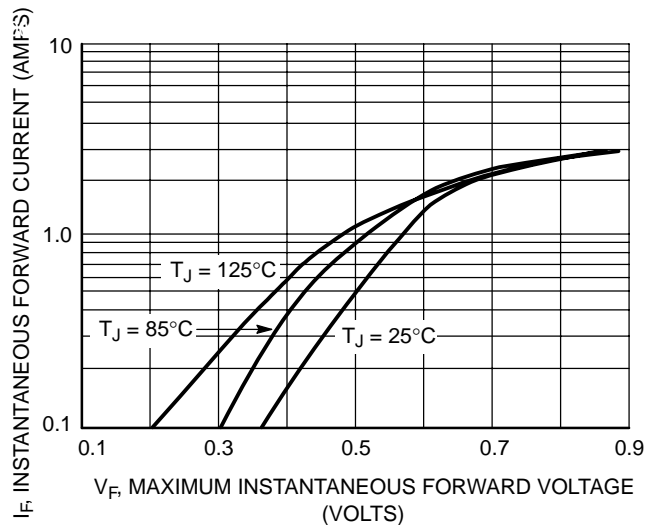


Figure 2. Maximum Forward Voltage

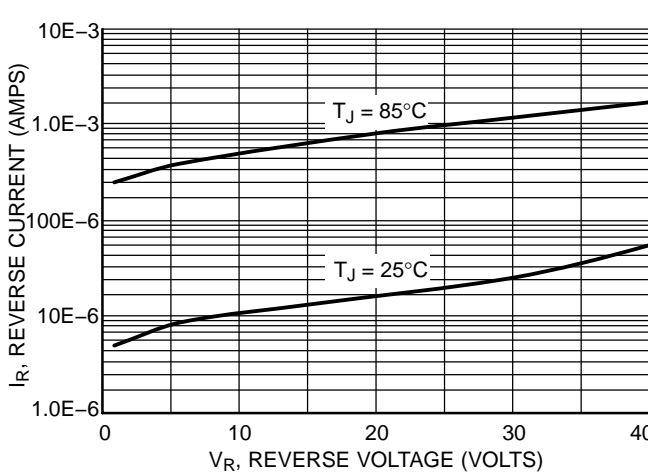


Figure 3. Typical Reverse Current

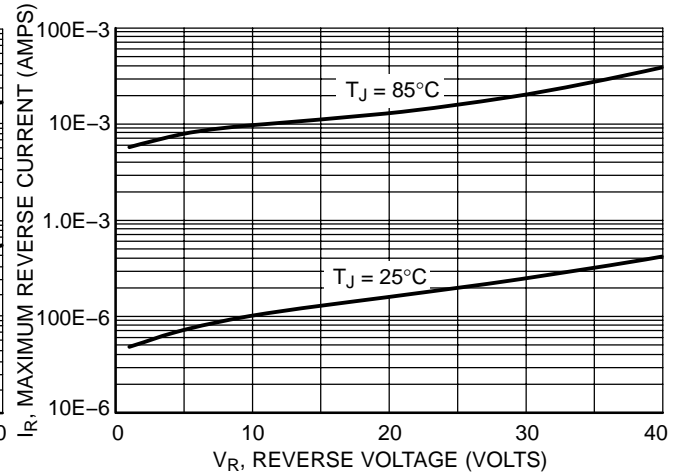


Figure 4. Maximum Reverse Current

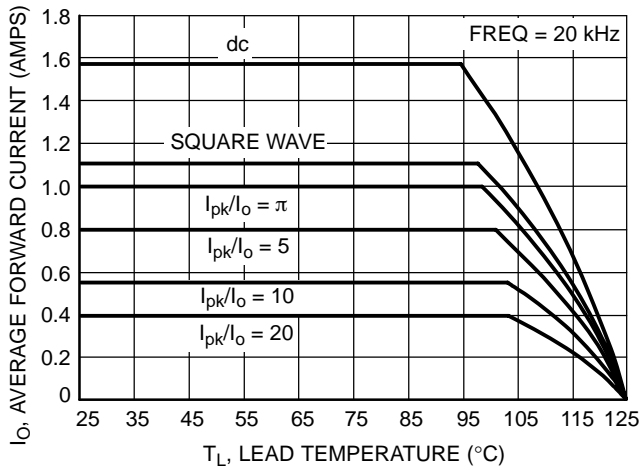


Figure 5. Current Derating

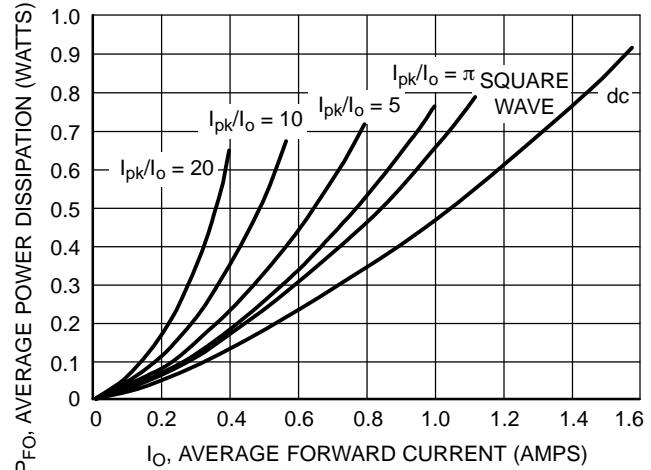


Figure 6. Forward Power Dissipation

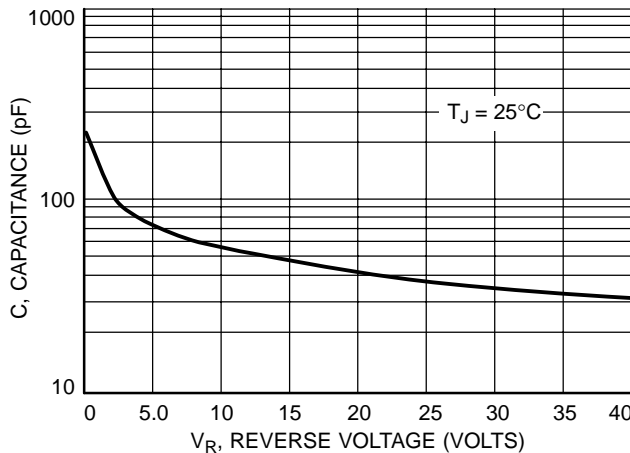


Figure 7. Capacitance

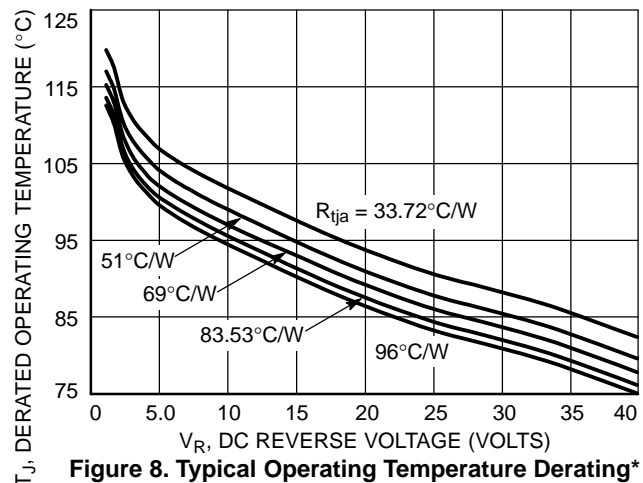


Figure 8. Typical Operating Temperature Derating\*

\* Reverse power dissipation and the possibility of thermal runaway must be considered when operating this device under any reverse voltage conditions. Calculations of  $T_J$  therefore must include forward and reverse power effects. The allowable operating  $T_J$  may be calculated from the equation:

$$T_J = T_{Jmax} - r(t)(P_f + P_r) \text{ where}$$

$r(t)$  = thermal impedance under given conditions,  
 $P_f$  = forward power dissipation, and  
 $P_r$  = reverse power dissipation

This graph displays the derated allowable  $T_J$  due to reverse bias under DC conditions only and is calculated as  $T_J = T_{Jmax} - r(t)P_r$ , where  $r(t) = R_{\theta JA}$ . For other power applications further calculations must be performed.

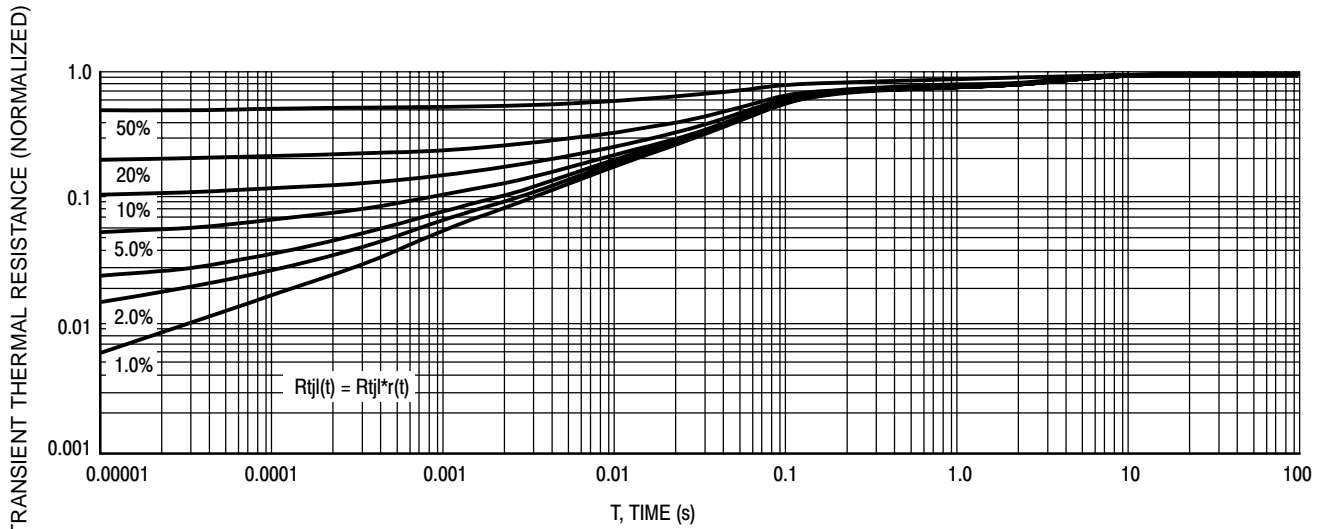


Figure 9. Thermal Response Junction to Lead

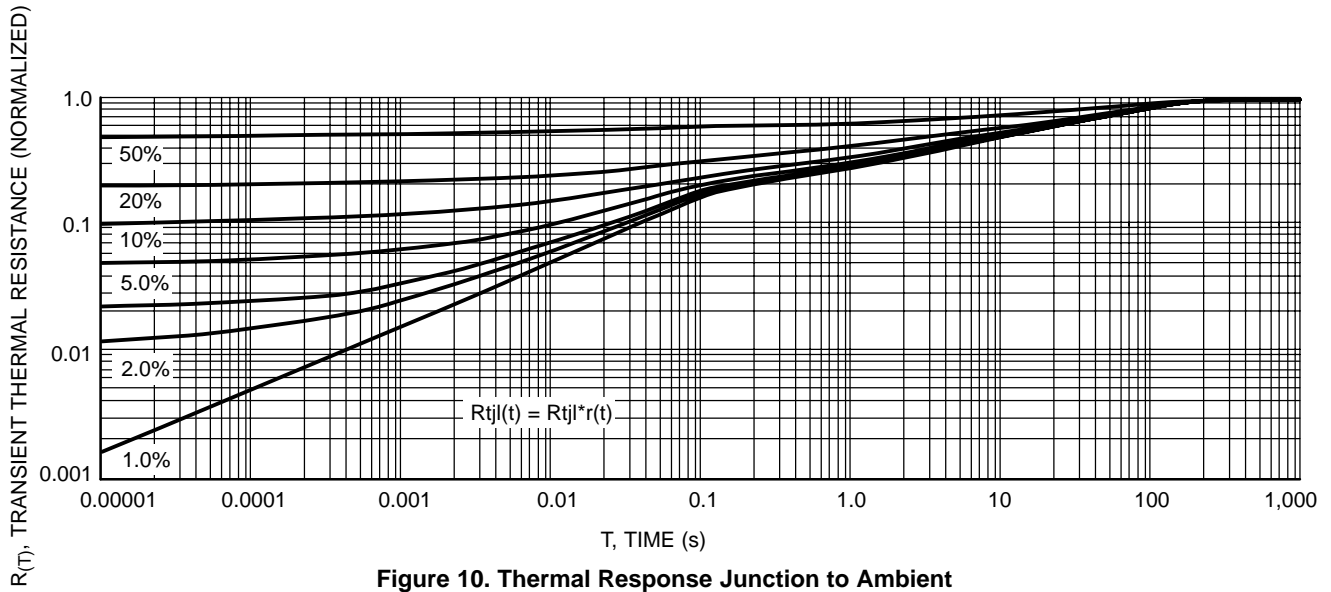
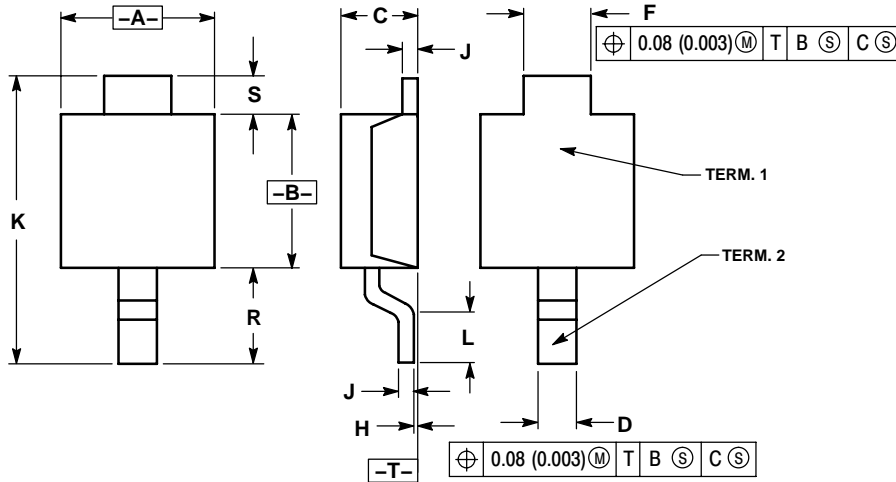


Figure 10. Thermal Response Junction to Ambient

# MBRM140

## PACKAGE DIMENSIONS

### POWERMITE CASE 457-04 ISSUE D

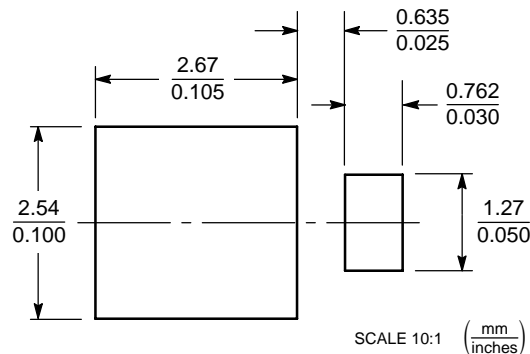


#### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.75	2.05	0.069	0.081
B	1.75	2.18	0.069	0.086
C	0.85	1.15	0.033	0.045
D	0.40	0.69	0.016	0.027
F	0.70	1.00	0.028	0.039
H	-0.05	+0.10	-0.002	+0.004
J	0.10	0.25	0.004	0.010
K	3.60	3.90	0.142	0.154
L	0.50	0.80	0.020	0.031
R	1.20	1.50	0.047	0.059
S	0.50 REF		0.019 REF	

### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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